

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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DATASHEET

SMD • TOP View LEDs EAPL3527GA0

PRELIMINARY



Features

- P-LCC-2 package.
- · White package.
- · Optical indicator.
- Colorless clear window.
- Wide viewing angle.
- Suitable for vapor-phase reflow, Infrared reflow and wave solder processes.
- Computable with automatic placement equipment.
- Available on tape and reel (8mm Tape).
- Pb-free
- The product itself will remain within RoHS compliant version.

Description

This series is available in soft orange, green, blue and yellow. Due to the package design, the LED has wide viewing angle and optimized light coupling by inter reflector. This feature makes ideal for light pipe application. The low current requirement makes this device ideal for portable equipment or any other application where power is at a premium.

Applications

- Automotive: backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- Light pipe application.
- · General use.



Device Selection Guide

Chip Materials	Emitted Color	Resin Color
InGaN/SiC	Brilliant Green	Water Clear

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V_{R}	5	V	
Forward Current	I _F	30	mA	
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA	
Power Dissipation	Pd	120	mW	
Junction Temperature	T _j	115	$^{\circ}$	
Operating Temperature	T_{opr}	-40 ~ +85	$^{\circ}\mathbb{C}$	
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\mathbb{C}$	
The second Descriptions	Rth _{J-A}	600	K/W	
Thermal Resistance	Rth _{J-S}	400	K/W	
ESD	ESD _{HBM}	2000	V	
(Classification acc. AEC Q101)	ESD _{MM}	200	V	
Soldering Temperature	T _{sol}	Reflow Soldering : 260 $^\circ\!\!\mathbb{C}$ for 10 sec. Hand Soldering : 350 $^\circ\!\!\mathbb{C}$ for 3 sec.		



Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Luminous Intensity	lv	72		450	mcd	I _F =20mA
Viewing Angle	$2\theta_{1/2}$		120		deg	$I_F=20mA$
Peak Wavelength	λр		518		nm	I _F =20mA
Dominant Wavelength	λd	523.5		535.5	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ		26		nm	I _F =20mA
Forward Voltage	V_{F}	2.7		3.7	V	I _F =20mA
Reverse Current	I _R			50	μΑ	$V_R=5V$

Note:

1. Tolerance of Luminous Intensity: ±11%

Tolerance of Dominant Wavelength: ±1nm
Tolerance of Forward Voltage: ±0.1V



Bin Range of Luminous Intensity

Bin Code	Min.	Max.	Unit	Condition
Q1	72	90		
Q2	90	112		
R1	112	140		
R2	140	180		L 00 A
S1	180	225	mcd	$I_F = 20 \text{mA}$
S2	225	285		
T1	285	360		
T2	360	450		

Note:

Tolerance of Luminous Intensity: ±11%

Bin Range of Dominant Wavelength

Bin Code	Min.	Max.	Unit	Condition
B13	523.5	525.5		
B14	525.5	527.5		
B15	527.5	529.5		
B16	529.5	531.5	mm nm	$I_F = 20 \text{mA}$
B17	531.5	533.5		
B18	533.5	535.5		

Note:

Tolerance of Dominant Wavelength: ±1nm

Bin Range of Forward Voltage

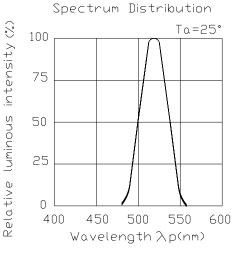
Bin Code	Min.	Max.	Unit	Condition
10	2.70	2.90		
11	2.90	3.10		
12	3.10	3.30	V	$I_F = 20 \text{mA}$
13	3.30	3.50		•
14	3.50	3.70		

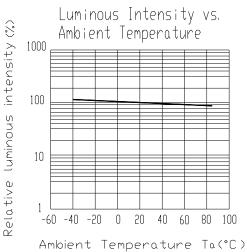
Note:

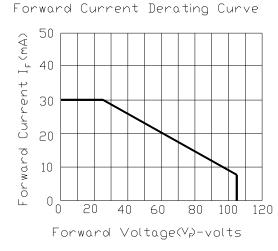
Tolerance of Forward Voltage: ±0.1V

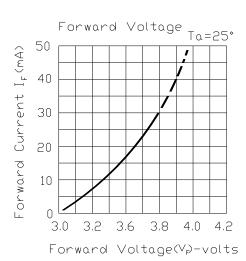


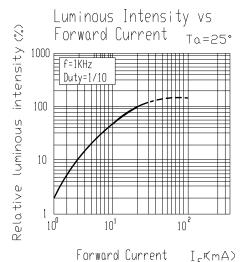
Typical Electro-Optical Characteristics Curves

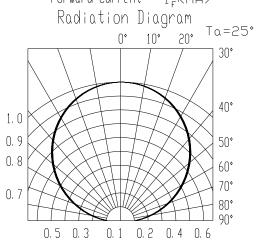






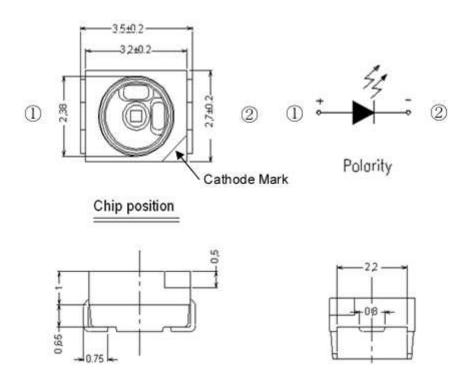








Package Dimension



Note: Tolerances unless mentioned ±0.1mm. Unit = mm



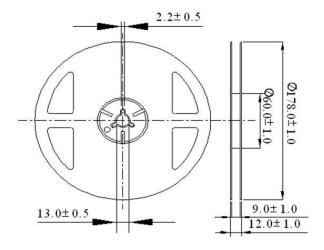
Moisture Resistant Packing Materials

Label Explanation



- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength RankREF: Forward Voltage Rank
- · LOT No: Lot Number

Reel Dimensions

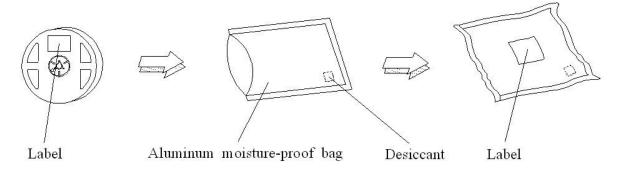


Carrier Tape Dimensions: Loaded Quantity 2000 pcs Per Reel

Note: Tolerances unless mentioned ± 0.1 mm. Unit = mm



Moisture Resistant Packing Process

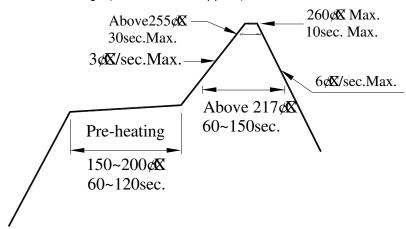


Note: Tolerances unless mentioned ±0.1mm. Unit = mm

Precautions for Use

1. Over-current-proof

1.1 Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).



2. Storage

- 2.1 Moisture proof bag should only be opened immediately prior to usage.
- 2.2 Environment should be less than 30° and 60° RH when moisture proof bag is opened.
- 2.3 After opening the package MSL Conditions stated on page 1 of this spec should not be exceeded.
- 2.4 If the moisture sensitivity card indicates higher than acceptable moisture, the component should be baked at min. 60deg +/-5deg for 24 hours.

3. Soldering Condition

- 3.1 Pb-free solder temperature profile
- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350° C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be



careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

Application Restrictions

High reliability applications such as military/aerospace, automotive safety/security systems, and medical equipment may require different product. If you have any concerns, please contact Everlight before using this product in your application. This specification guarantees the quality and performance of the product as an individual component. Do not use this product beyond the specification described in this document.

Revision History

Rev.	Modified date	File modified contents
1	2014/4/28	New Spec